

DOCKET NUMBER: 213480US01pmh

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:  
Sei TSUNODA, et al.

: GROUP: 2812

SERIAL NUMBER: 09/942,626

: ATTENTION:  
Application Division  
Customer Corrections

FILED: AUGUST 31, 2001

FOR: LOW DIELECTRIC CONSTANT MATERIAL HAVING THERMAL RESISTANCE,  
INSULATION FILM BETWEEN SEMICONDUCTOR LAYERS USING THE SAME,  
AND SEMICONDUCTOR DEVICE

SECOND REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

The Patent Office is requested to provide a corrected Official Filing Receipt for the attached. If you have any questions, please do not hesitate to contact us.

No fees are required. However, in the event that a fee is required, please charge the appropriate amount to our Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.


Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,  
MAIER & NEUSTADT, P.C.

RECEIVED

AUG 28 2002

TC 1700

  
Norman F. Oblon  
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**22850**

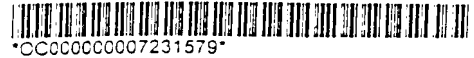
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## UNITED STATES PATENT AND TRADEMARK OFFICE

COMMISSIONER FOR PATENTS  
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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/942,626	08/31/2001	2812	840	213480US0	0	3	1

22350  
OBLON SPIVAK MCCLELLAND MAIER & NEUSTADT PC  
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CORRECTED FILING RECEIPT

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Date Mailed: 12/26/2001

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

## Applicant(s)

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## Assignment For Published Patent Application

MITSUBISHI DENKI KABUSHIKI KAISHA, Chiyoda-ku, JAPAN;

Domestic Priority data as claimed by applicant

## Foreign Applications

JAPAN 153600/1999 01/06/1999

If Required, Foreign Filing License Granted 10/22/2001

Projected Publication Date: 03/14/2002

Non-Publication Request: No

Early Publication Request: No

## Title

Low dielectric constant material having thermal resistance, insulation film between semiconductor layers using the same, and semiconductor device

## Preliminary Class

438

PLEASE NOTE THAT THE FOREIGN APPLICATION INFORMATION IS NOT BEING CLAIMED.

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DEC 31 2001OBLON, SPIVAK, McCLELLAND  
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